



Material Content Data Sheet



Sales Product Name		ICE2QR4765Z		Issued		1. August 2018			
MA#		MA001860908							
Package		PG-DIP-7-3		Weight*		644.83 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.794	0.43	0.43	4333	4333	
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75		
	non noble metal	zinc	7440-66-6	0.194	0.03		300		
	non noble metal	iron	7439-89-6	3.872	0.60		6005		
wire	non noble metal	copper	7440-50-8	157.218	24.38	25.02	243811	250191	
	noble metal	gold	7440-57-5	0.413	0.06	0.06	641	641	
	encapsulation	organic material	carbon black	1333-86-4	2.353	0.36		3649	
encapsulation	plastics	epoxy resin	-	63.534	9.85		98528		
	inorganic material	silicondioxide	60676-86-0	404.735	62.78	72.99	627657	729834	
	leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10017	10017
plating	noble metal	silver	7440-22-4	1.594	0.25	0.25	2472	2472	
glue	plastics	epoxy resin	-	0.283	0.04		440		
	noble metal	silver	7440-22-4	1.336	0.21	0.25	2072	2512	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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